

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE ABSTRACT OF THE DISCLOSURE:

The Abstract of the Disclosure has been amended as follows:

ABSTRACT

~~The present invention relates to a~~A slurry for polishing copper-based metal containing a silica polishing material, an oxidizing agent, an amino acid, a triazole-based compound and water, wherein a content ratio of ~~said~~ amino acid to ~~said~~ triazole-based compound (amino acid / triazole-based compound (weight ratio)) is 5 to 8.

ABSTRACT

A slurry for polishing copper-based metal containing a silica polishing material, an oxidizing agent, an amino acid, a triazole-based compound and water, wherein a content ratio of amino acid to triazole-based compound (amino acid / triazole-based compound (weight ratio)) is 5 to 8.